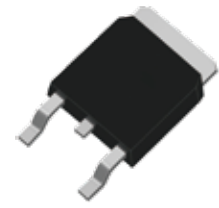


FEATURES

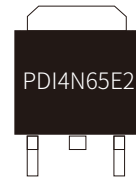
- | Low Gate Charge
- | Low ON Resistance
- | Improved dv/dt Capability
- | 100% Avalanche Tested



TO-252

APPLICATION

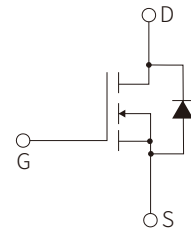
- | Switching Mode Power Supplies (SMPS)
- | PWM Motor Controls
- | LED Lighting
- | Adapter



Marking

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003



Schematic Symbol

ABSOLUTE MAXIMUM RATINGS (T_A=25°C)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	650	V
Continuous Drain Current	I _D	T _c =25°C	4 ⁽¹⁾
		T _c =100°C	2.5 ⁽¹⁾
Drain current pulsed ⁽²⁾	I _{DM}	16 ⁽¹⁾	A
Gate-Source Voltage	V _{GS}	±30	V
Single pulsed Avalanche Energy ⁽³⁾	E _{AS}	54	mJ
Peak diode Recovery dv/dt ⁽⁴⁾	dv/dt	5	V/ns
Total power dissipation (@T _c =25°C)	P _D	173	W
Derating Factor above 25°C	P _D	1.38	W/°C
Operating Junction Temperature & Storage Temperature	T _{STG} , T _J	-55 to +150	°C
Maximum lead temperature for soldering purpose	T _L	260	°C
Thermal resistance, Junction to case (Maximum)	R _{thjc}	0.72	°C/W
Thermal resistance, Junction to ambient (Maximum)	R _{thja}	100	°C/W

Notes

1. Drain current is limited by maximum junction temperature.
2. Repetitive rating : pulse width limited by junction temperature.
3. L = 12mH, I_{AS} = 3A, V_{DD} = 50V, R_G = 25Ω, Starting at T_J = 25°C
4. I_{SD} ≤ I_D, di/dt = 100A/us, V_{DD} ≤ BV_{DSS}, Starting at T_J = 25°C

ELECTRICAL CHARACTERISTICS (T_A=25°C)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	650			V
Breakdown voltage temperature coefficient	ΔBV _{DSS} / ΔT _J	I _D =250μA, referenced to 25°C		0.7		V/°C
Zero Gate Voltage Drain current	I _{DSS}	V _{DS} =650V, V _{GS} =0V			1	μA
		V _{DS} =520V, T _C =125°C			10	μA
Gate Leakage Current	I _{GSS}	V _{GS} =30V, V _{DS} =0V			100	nA
		V _{GS} =-30V, V _{DS} =0V			-100	nA
Off Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.5	3.5	4.5	V
Drain-Source On-Resistance (note2)	R _{DS(on)}	V _{GS} =10V, I _D =2A		2.5	3.0	Ω
Forward Tran conductance	gFS	V _{DS} =10V, I _D =2A		3		S
Dynamic Characteristics						
Input capacitance	C _{ISS}	V _{DS} = 25V, V _{GS} = 0V, f=1MHz		506		pF
Output capacitance	C _{OSS}			42.5		pF
Reverse Transfer capacitance	C _{rss}			3.5		pF
Turn-on Delay Time	td(on)	V _{DS} =325V, I _D =4A, R _G =25Ω V _{GS} =10V		19.3		ns
Rising time	tf			12		ns
Turn-off Delay Time	td(off)			35.3		ns
Input capacitance	tf			13		ns
Total gate charge	Q _g	V _{DS} =325V, I _D =4A, V _{GS} =10V		11.2		nC
Gate-source charge	Q _{gs}			2.7		nC
Gate-drain charge	Q _{gd}			4.3		nC
Continuous source current	I _S	Integral reverse p-n Junction diode in the MOSFET			4	A
Pulsed source current	I _{SM}				16	A
Diode forward voltage drop.	V _{SD}	I _S =4A, V _{GS} =0V		0.9	1.3	V
Reverse recovery time	T _{rr}	I _S =4A, V _{GS} =0V, di _r /dt=100A/μs		335		ns
Reverse recovery Charge	Q _{rr}				1.84	

CHARACTERISTIC CURVES

Fig.1 Output characteristics

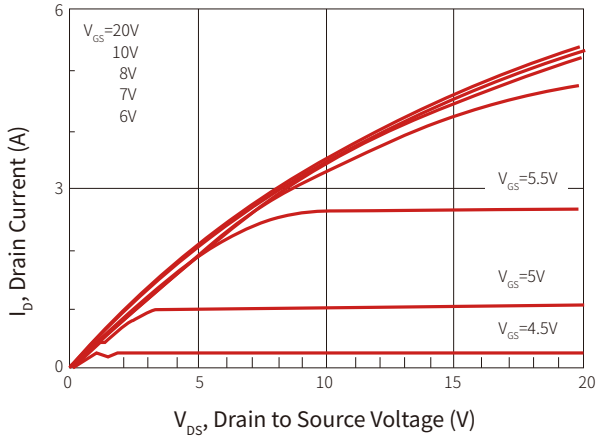


Fig.2 Reverse Characteristics

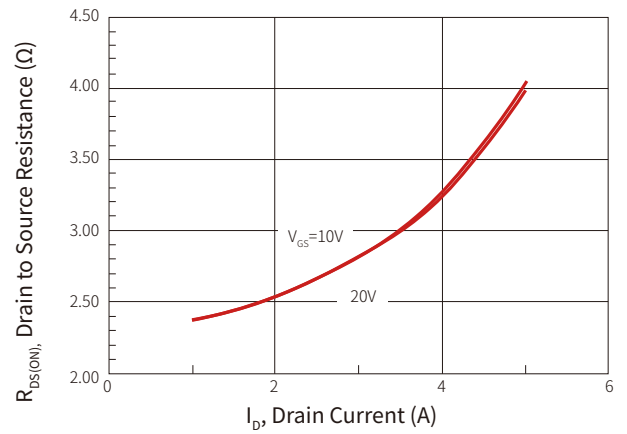


Fig.3 Gate charge characteristics

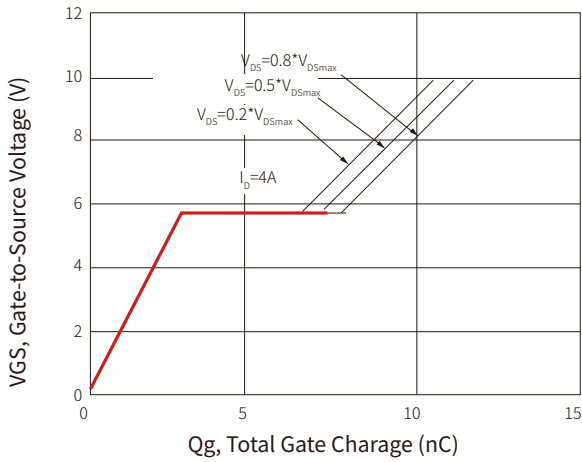


Fig.4 Capacitance Characteristics

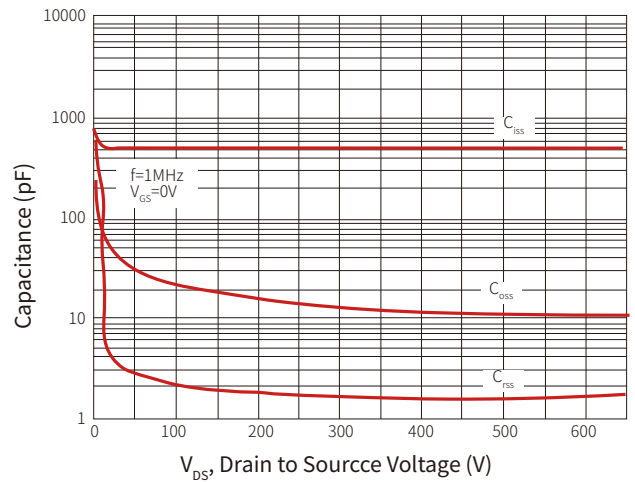


Fig.5 $R_{DS(ON)}$ vs junction temperature

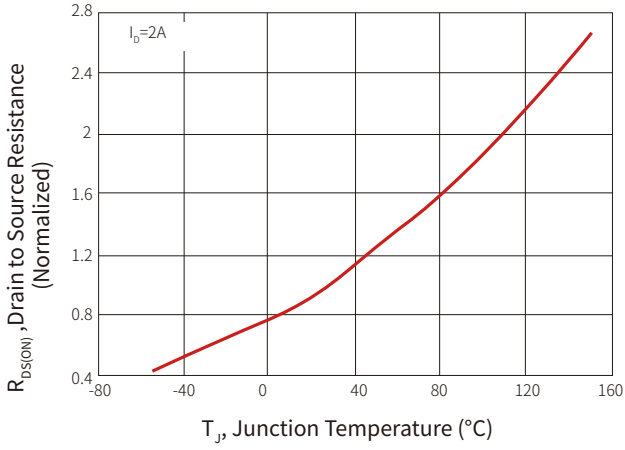


Fig. 6 BV_{DSS} vs junction temperature

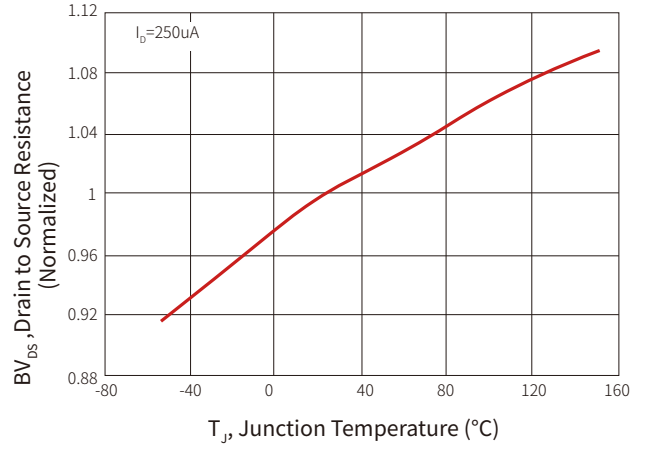


Fig.7 Forward characteristics of reverse diode

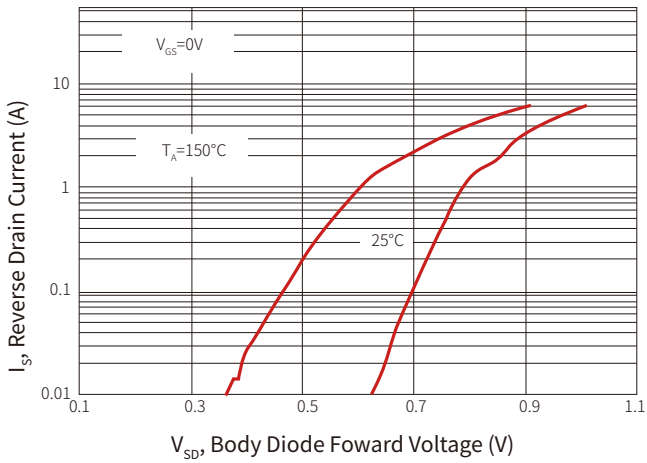


Fig.8 Transfer characteristics

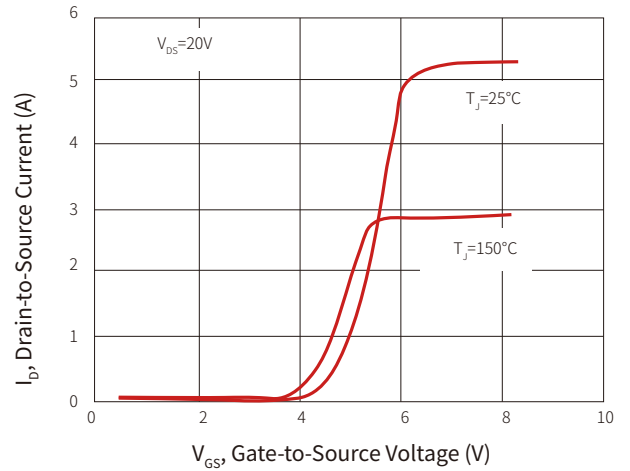


Fig.9 $V_{GS(TH)}$ vs junction temperature

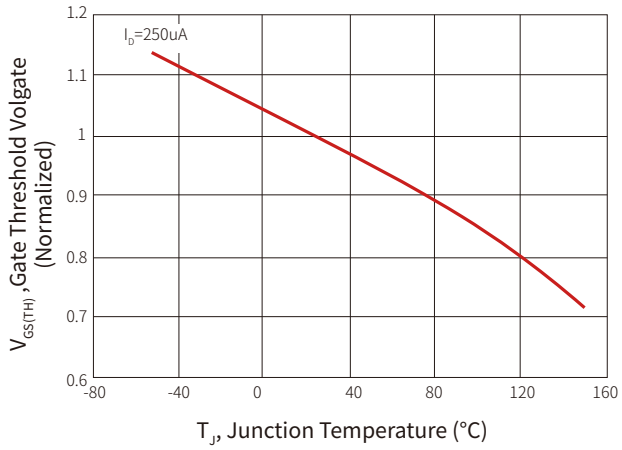


Fig. 10 Safe operating area

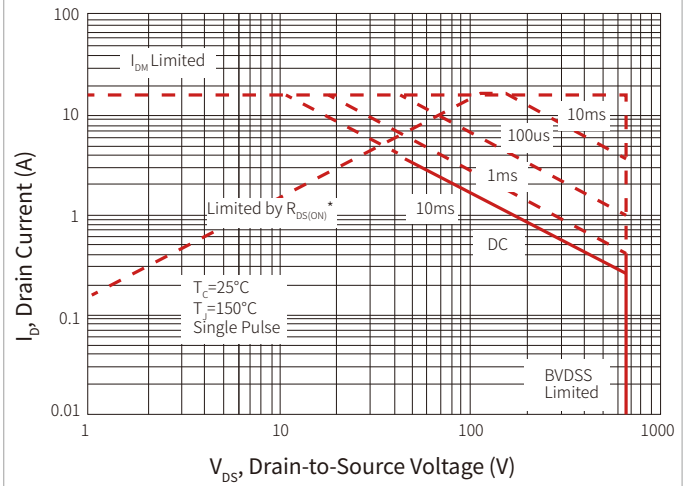


Fig.11 Transient thermal impedance

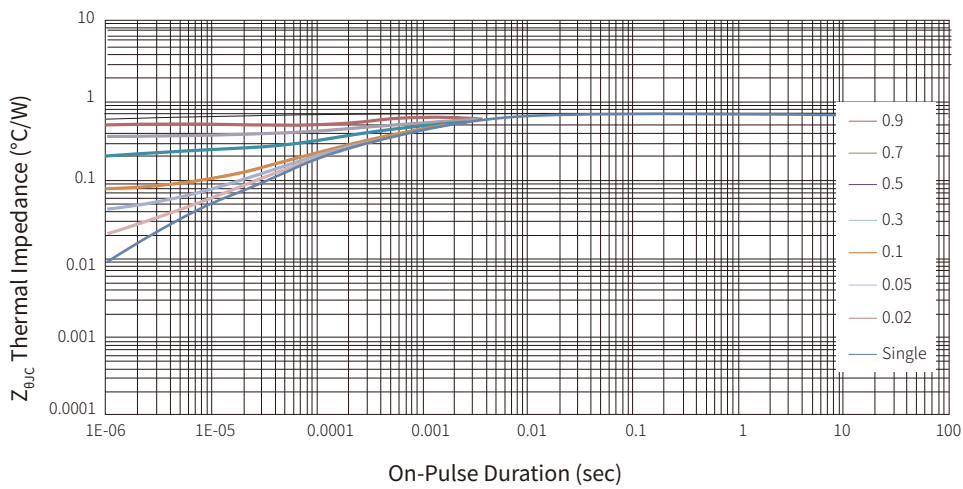


Fig.12 Gate charge test circuit & waveform

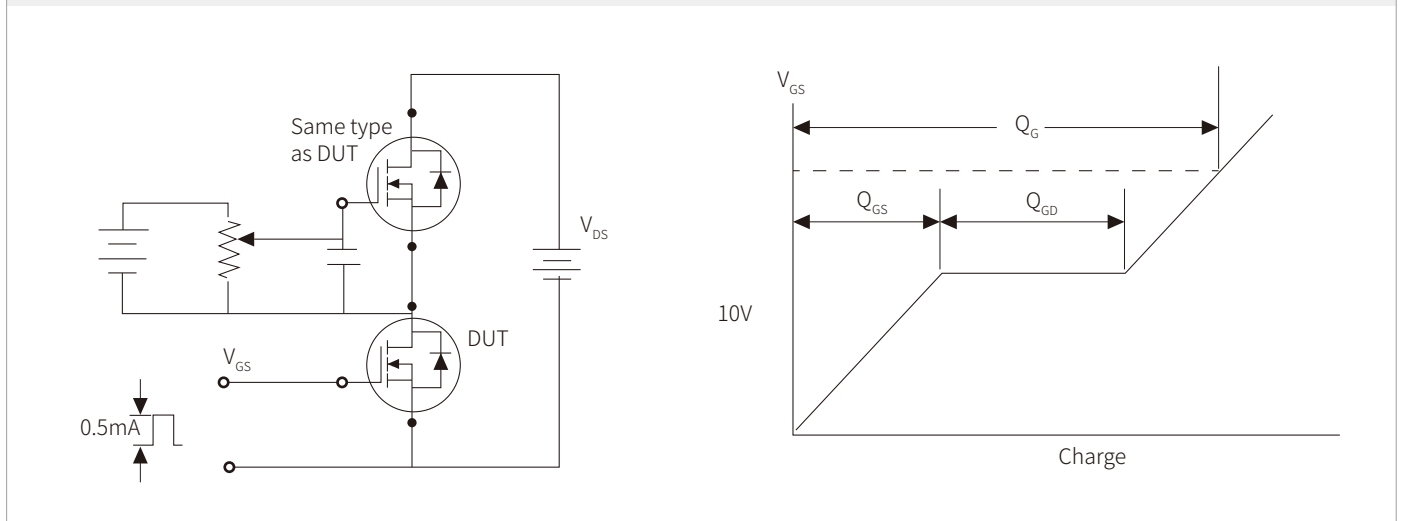


Fig.13 Switching time test circuit & waveform

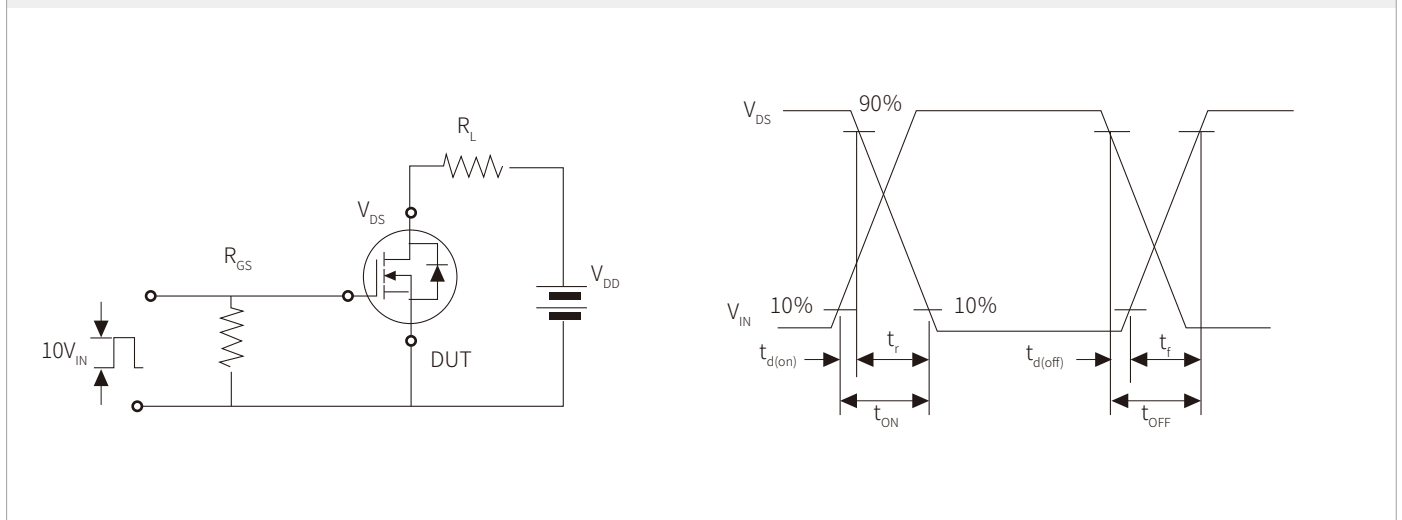


Fig.14 Unclamped Inductive switching test circuit & waveform

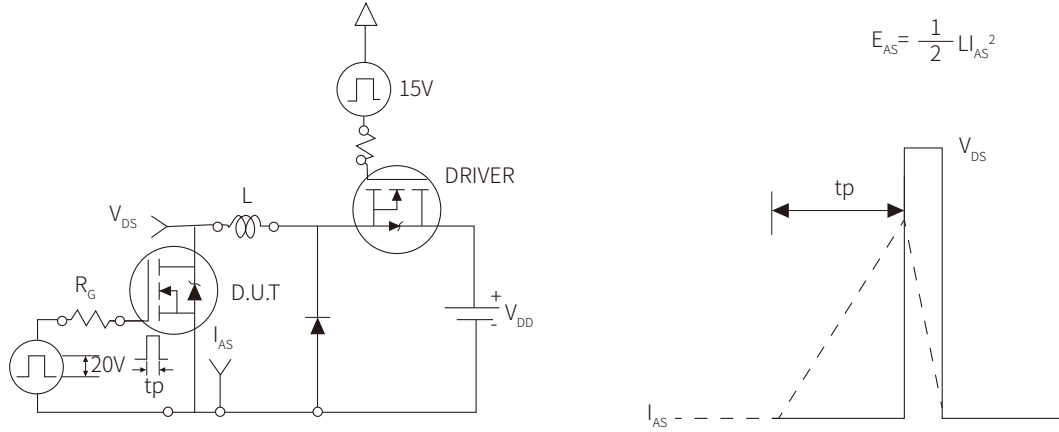
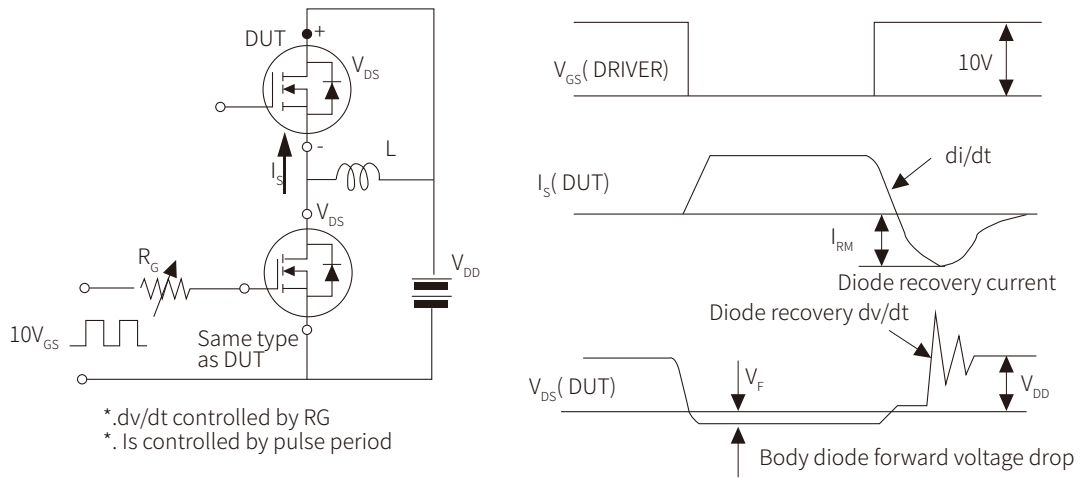
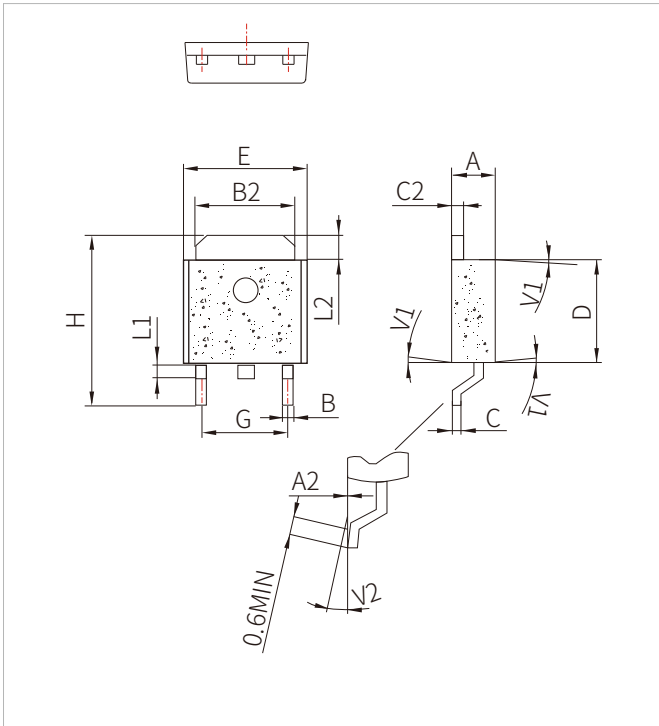


Fig.15 Peak diode recovery dv/dt test circuit & waveform



TO-252 PACKAGE MECHANICAL DATA



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0.03		0.23	0.001		0.009
B	0.55		0.65	0.022		0.026
B2	5.10		5.40	0.200		0.213
C	0.45		0.62	0.018		0.024
C2	0.48		0.62	0.019		0.024
D	6.00		6.20	0.236		0.244
E	6.40		6.80	0.252		0.268
G	4.40		4.70	0.173	0.1	0.185
H	9.35		10.7	0.368		0.421
L1	1.30		1.70	0.051	0.143	0.067
L2	1.37		1.50	0.054		0.059
V1		4°			0.130	
V2	0°		8°	0°		8°

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SNMD4N65	TO-252	5000PCS	13"

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